



SEMITRANS® 10

IGBT R8 Modules

SKM1000GB17R8

Features*

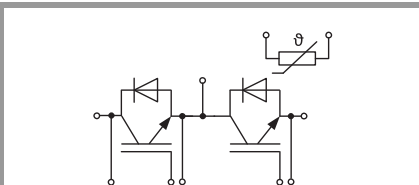
- Symmetrical current sharing
- Low-inductive module design
- High mechanical robustness
- UL recognized, file no. E63532

Typical Applications

- Motor Drives
- UPS Systems
- Solar Inverters

Remarks

Recommended $T_{jop} = -40 \dots +150^\circ\text{C}$



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Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
IGBT				
V _{CES}	T _j = 25 °C		1700	V
I _C	T _j = 175 °C	T _c = 25 °C	1574	A
		T _c = 100 °C	1027	A
I _{Cnom}			1000	A
I _{CRM}	I _{CRM} = 2 x I _{Cnom}		2000	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 1200 V V _{GE} ≤ 15 V V _{CES} ≤ 1700 V	T _j = 150 °C	10	µs
T _j			-40 ... 175	°C
Inverse diode				
V _{RRM}	T _j = 25 °C		1700	V
I _F	T _j = 175 °C	T _c = 25 °C	1449	A
		T _c = 100 °C	905	A
I _{Fnom}			1000	A
I _{FRM}	I _{FRM} = 2 x I _{Fnom}		2000	A
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 25 °C		6240	A
T _j			-40 ... 175	°C
Module				
T _{stg}			-40 ... 150	°C
V _{isol}	AC sinus 50 Hz, t = 1 min		4000	V

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
IGBT						
V _{CE(sat)}	I _C = 1000 A V _{GE} = 15 V chiplevel	T _j = 25 °C		1.66	1.99	V
		T _j = 150 °C		2.01	2.33	V
V _{CE0}	chiplevel	T _j = 25 °C		1.06	1.12	V
		T _j = 150 °C		0.95	1.05	V
r _{CE}	V _{GE} = 15 V chiplevel	T _j = 25 °C		0.60	0.87	mΩ
		T _j = 150 °C		1.06	1.28	mΩ
V _{GE(th)}	V _{GE} =V _{CE} , I _C = 36 mA		5	5.8	6.5	V
I _{CES}	V _{GE} = 0 V, V _{CE} = 1700 V, T _j = 25 °C				6.0	mA
C _{ies}	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz		90.0		nF
C _{oes}		f = 1 MHz		3.00		nF
C _{res}		f = 1 MHz		0.24		nF
Q _G	V _{GE} = -15V / +15V			5640		nC
R _{Gint}	T _j = 25 °C			1.8		Ω
t _{d(on)}	V _{CC} = 900 V	T _j = 150 °C		476		ns
t _r	I _C = 1000 A	T _j = 150 °C		105		ns
E _{on}	V _{GE} = +15/-15 V R _{G on} = 0.7 Ω	T _j = 150 °C		465		mJ
t _{d(off)}	R _{G off} = 0.7 Ω	T _j = 150 °C		713		ns
t _f	di/dt _{on} = 7.8 kA/μs di/dt _{off} = 4.8 kA/μs	T _j = 150 °C		158		ns
E _{off}	dv/dt = 4600 V/μs L _s = 24 nH	T _j = 150 °C		332		mJ
R _{th(j-c)}	per IGBT				0.03	K/W
R _{th(c-s)}	per IGBT (λ _{grease} =0.81 W/(m*K))			0.016		K/W



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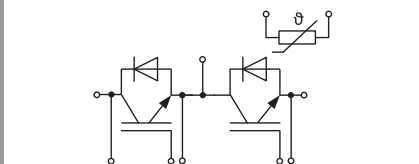
Typical Applications

- Motor Drives
- UPS Systems
- Solar Inverters

Remarks

Recommended $T_{jop} = -40 \dots +150^{\circ}\text{C}$

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
V _F = V _{EC}	I _F = 1000 A	T _j = 25 °C		1.78	2.12	V
	V _{GE} = 0 V chiplevel	T _j = 150 °C		1.81	2.14	V
V _{F0}	chiplevel	T _j = 25 °C		1.32	1.56	V
		T _j = 150 °C		1.08	1.22	V
r _F	chiplevel	T _j = 25 °C		0.46	0.56	mΩ
		T _j = 150 °C		0.73	0.92	mΩ
I _{RRM}	I _F = 1000 A	T _j = 150 °C		711		A
Q _{rr}	di/dt _{off} = 8.1 kA/μs	T _j = 150 °C		325		μC
E _{rr}	V _{GE} = -15 V V _{CC} = 900 V	T _j = 150 °C		159		mJ
R _{th(j-c)}	per diode				0.042	K/W
R _{th(c-s)}	per diode (λ _{grease} =0.81 W/(m*K))			0.017		K/W
Module						
L _{CE}				10		nH
R _{CC'+EE'}	measured per switch, T _C = 25 °C			0.2		mΩ
R _{th(c-s)1}	calculated without thermal coupling (λ _{grease} =0.81 W/(m*K))			0.0041		K/W
R _{th(c-s)2}	including thermal coupling, T _s underneath module (λ _{grease} =0.81 W/(m*K))			0.007		K/W
M _s	to heat sink M5		4		6	Nm
M _t		to terminals M8	8		10	Nm
		to terminals M4	1.8		2.1	Nm
w					1250	g
Temperature Sensor						
R ₁₀₀	T _C =100°C (R ₂₅ =5 kΩ)			493 ± 5%		Ω
B _{100/125}	R(T)=R ₁₀₀ exp[B _{100/125} (1/T-1/T ₁₀₀)]; T[K];			3550 ±2%		K



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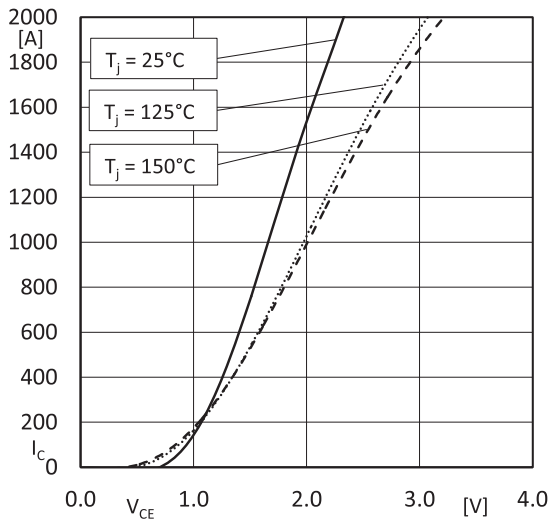


Fig. 1: Output characteristics IGBT (typical); $I_C = f(V_{CE})$; $V_{GE} = 15V$; (chiplevel)

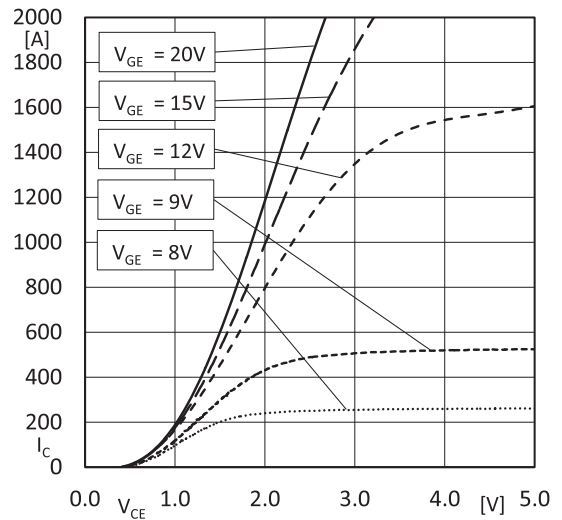


Fig. 2: Output characteristics IGBT (typical); $I_C = f(V_{CE})$; $T_j = 150^\circ C$; (chiplevel)

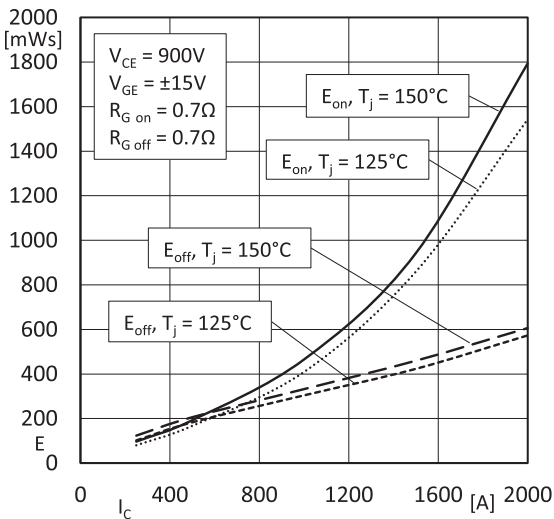


Fig. 3: Switching losses IGBT (typical); $E=f(I_C)$

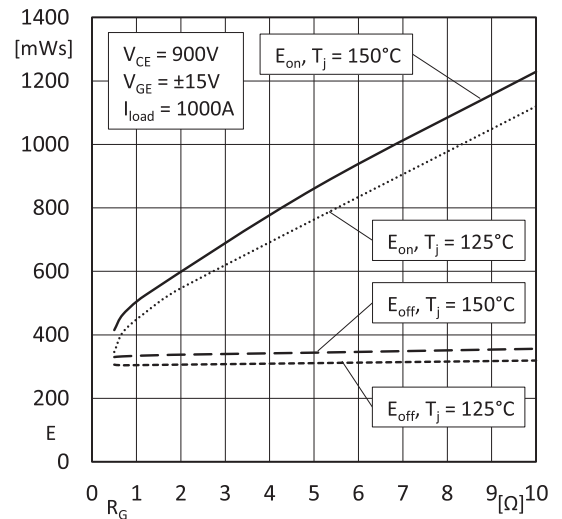


Fig. 4: Switching losses IGBT (typical); $E=f(R_G)$

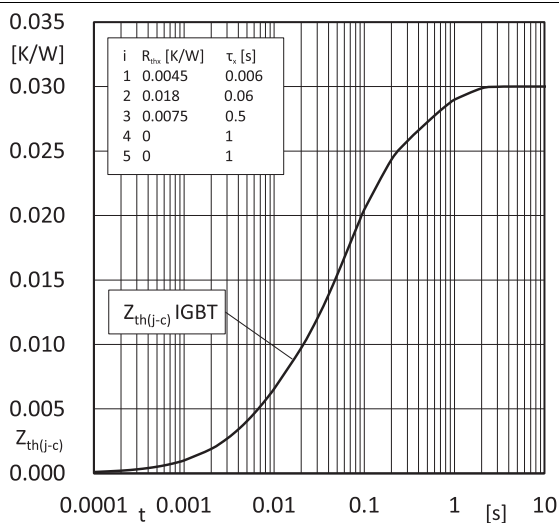


Fig. 5: Transient thermal impedance IGBT

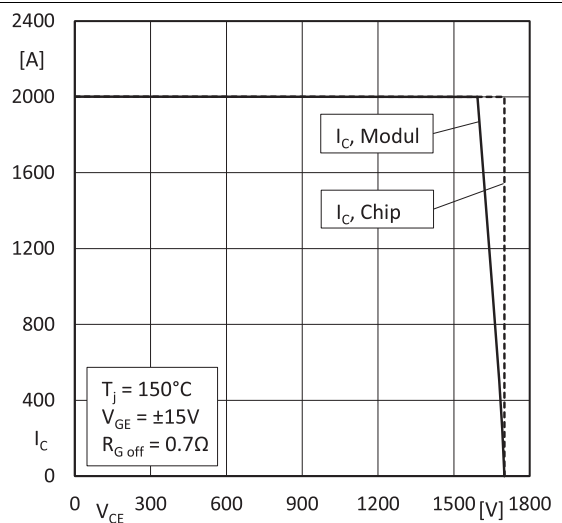


Fig. 6: RBSOA IGBT

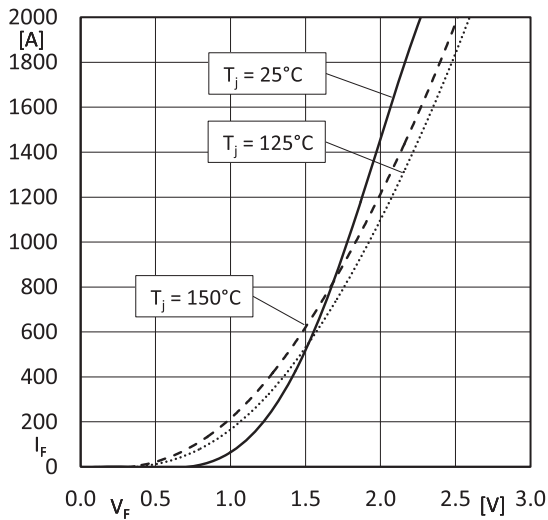


Fig. 7: Forward charact. Diode (typical); $I_F = f(V_F)$; (chipllevel)

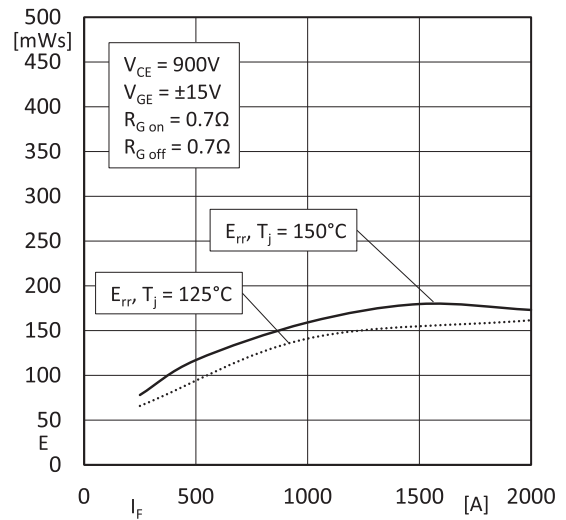


Fig. 8: Switching losses Diode (typical); $E = f(I_F)$

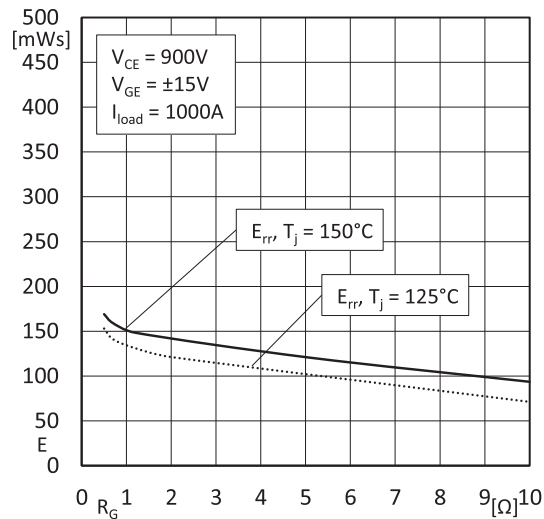


Fig. 9: Switching losses Diode (typical); $E = f(R_G)$

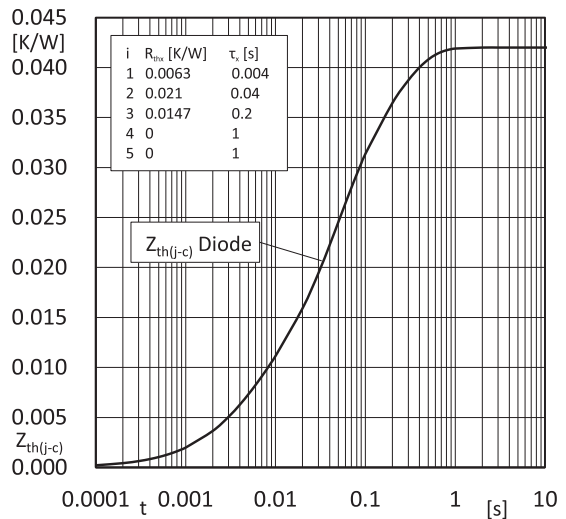


Fig. 10: Transient thermal impedance Diode

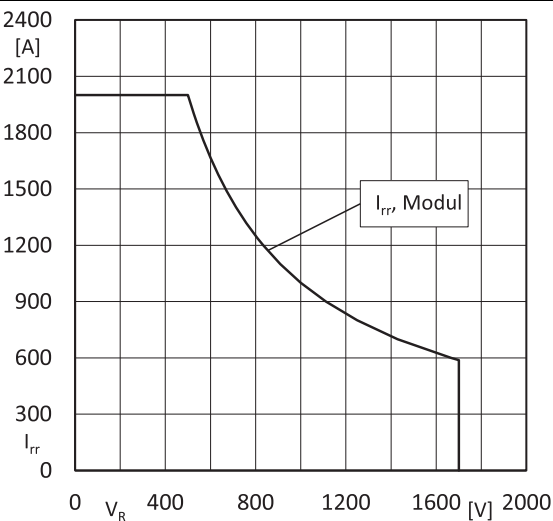


Fig. 11: RBSOA Diode

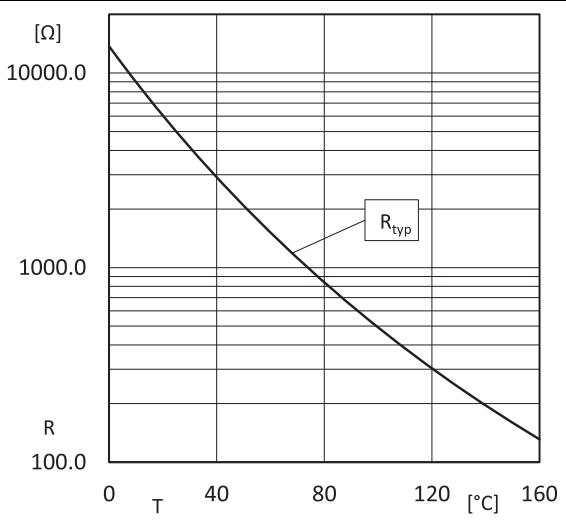


Fig. 12: NTC characteristics (typical)

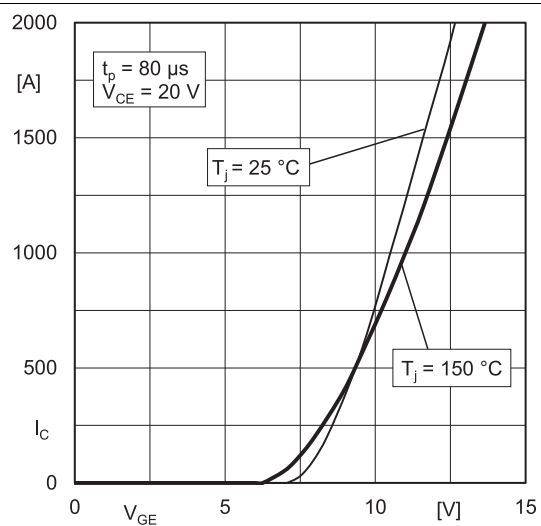


Fig. 13: Typ. transfer characteristic

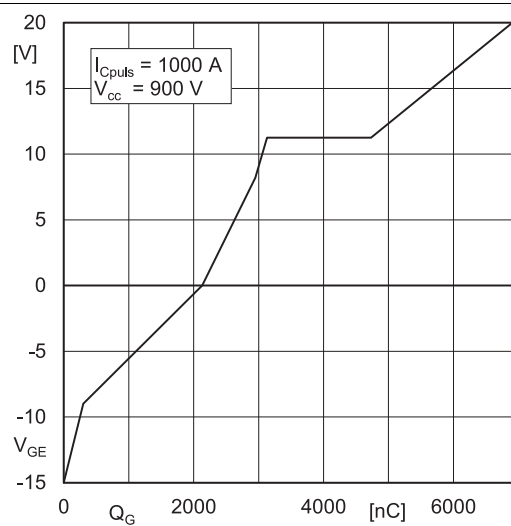
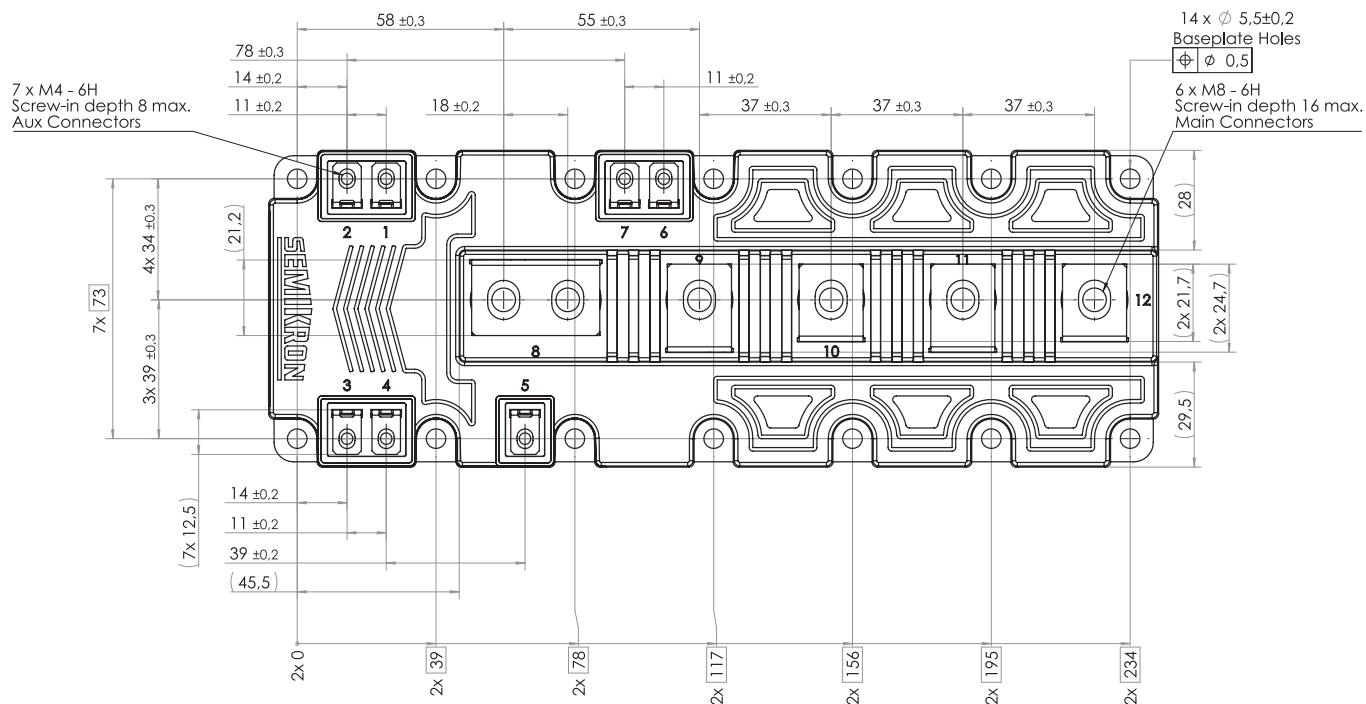
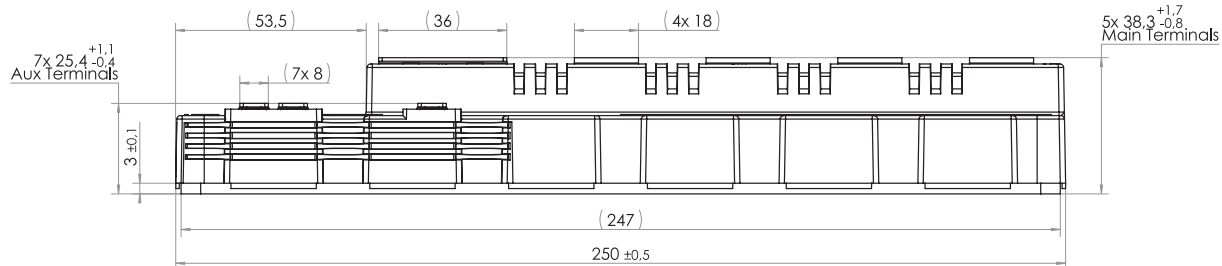
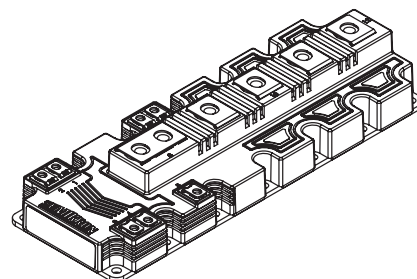
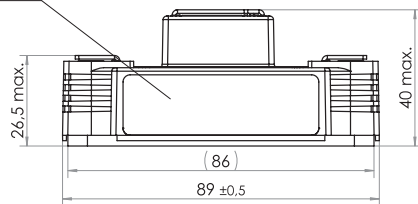


Fig. 14: Typ. gate charge characteristic

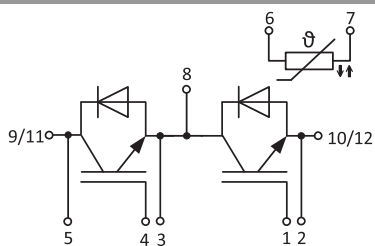
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Module label



- Dimensions in mm
- General tolerances $\pm 0.5\text{mm}$

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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

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